

## CERTIFICATION OF COMPLIANCE AND CHEMICAL CONTENT FOR PRODUCTS WITH LEAD-FREE SOLDER

The undersigned, an employee and authorized representative of National Semiconductor, certifies that to the knowledge of National Semiconductor as of the date below:

- ❖ National Semiconductor products with lead-free solder are RoHS compliant. Most such products are designated "NOPB."
- ❖ Some RoHS compliant products may contain lead in exempt applications.
- ❖ Other than lead in exempt applications, RoHS restricted substances are not intentionally added and do not exceed RoHS maximum concentration values in any homogeneous material.
- ❖ Packing materials contain less than a sum total concentration of 100 ppm of lead, mercury, hexavalent chromium and cadmium.
- ❖ Plastic materials do not contain cadmium greater than 5 ppm.
- ❖ National Semiconductor products and packing materials do not contain other banned substances listed below
- ❖ National Semiconductor products do not contain and are not manufactured with ozone depleting substances subject to The Montreal Protocol on Substances that Deplete the Ozone Layer and U.S. Clean Air Act, Title VI.

### *Banned Substances*

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- Asbestos
  - Azo compounds
  - Cadmium and cadmium compounds
  - Ethylene glycol ethers and related compounds
  - Halogenated dioxins and furans
  - Hexavalent chromium compounds
  - Lead and lead compounds, with exceptions
  - Mercury and mercury compounds
  - Ozone depleting substances
  - Polybrominated biphenyls (PBBs) and diphenyl ethers (PBDEs)
  - Polychlorinated biphenyls (PCBs), phenyls, terphenyls and naphthalenes
  - Radioactive substances
  - Short chain chlorinated paraffins
  - Tributyltin, bis(tributyltin) oxide, triphenyltin, and other organic tin compounds
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Signature:



Name/Title: **Gerry Fields, Vice President of Quality**

Date: **September 23, 2005**

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